

**Polymer
 PTC Devices**

Surface mount fuses

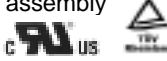
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LP-NSM110

Features

- Very small size of 1206
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL, CSA, TUV



Product Dimensions (mm)

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-NSM110	3.50	1.80	1.30	0.60	0.20

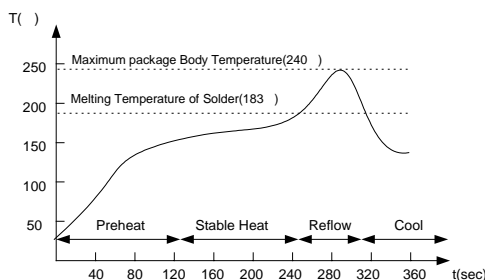
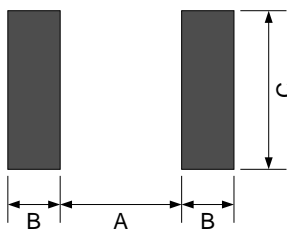


Electrical Characteristics

Part number	I_H (A)	I_T (A)	V_{max} (V)	I_{max} (A)	T_{trip} Current(A) Time(S)	Pd_{typ} (W)	R_{min} (Ω)	R_{1max} (Ω)
LP-NSM110	1.10	1.80	6	40	8.0 3.00	0.6	0.055	0.21

I_H =Hold current: maximum current at which the device will not trip at 25 still air.
 I_T =Trip current: minimum current at which the device will always trip at 25 still air.
 V_{max} =Maximum voltage device can withstand without damage at rated current.
 I_{max} =Maximum fault current device can withstand without damage at rated voltage.
 T_{trip} =Maximum time to trip(s) at assigned current.
 Pd_{typ} =Typical power dissipation: typical amount of power dissipated by the device when in state air environment.
 R_{min} =Minimum device resistance at 25 prior to tripping.
 R_{1max} =Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-NSM110	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.
 * Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Package Information

Tape & Reel: 3000pcs per reel.